xLED

xLED-GE-8030 Pin Fin LED Heat Sink Φ80mm for GE Lighting

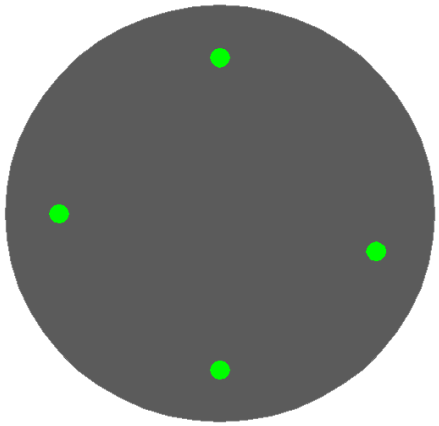
Features VS Benefits

* The xLED-GE-8030 GE Lighting Pin Fin LED Heat Sinks are specifically designed for luminaires using the GE Lighting LED engines.
* Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
* For spotlight and downlight designs from 1,000 to 2,600 lumen.
* Thermal resistance range Rth 3.13°C/W.
* Modular design with mounting holes foreseen for direct mounting of GE lighting Infusion™ LED engines.
* Diameter 80.0mm - standard height 30.0mm Other heights on request.
* Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

* Below you find an overview of GE Lighting engines COB's and LED modules which standard fit on the Pin Fin LED Heat Sinks.
* In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of LED Pin Fin LED Heat Sink.

GE Lighting



GE lighting LED engines for which Zhaga book5 LED Modules holders are available.

For the GE lighting Infusion™ M LED modules.

Infusion™ M3000

M3000/827/W/G4;
M3000/830/W/G4;
M3000/835/W/G4;
M3000/840/W/G4;
M3000/930/W/G4;

Infusion™ M4500

M4500/827/W/G4;
M4500/830/W/G4;
M4500/835/W/G4;
M4500/840/W/G4;
M4500/930/W/G4;

For the GE lighting Infusion™ DLM LED modules.

Infusion™ DLMM3000

DLM3000/927;
DLM3000/930;
DLM3000/935;
DLM3000/940;

Infusion™ DLM4000

DLM4000/927;
DLM4000/930;
DLM4000/935;
DLM4000/940;

Please refer to the "http://www.gelighting.com/LightingWeb/emea/" data provided on the manual.

Zhaga Book5 Green indicator marks:
Direct mounting with machine screws M3.5x6.5mm;

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Mingfa TECH

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Mounting Options and Drawings & Dimensions

Example:xLED-GE-8030-B-1

Example:xLED-GE-80 1 - 2 - 3

1 Height (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

Ex.order code - 12

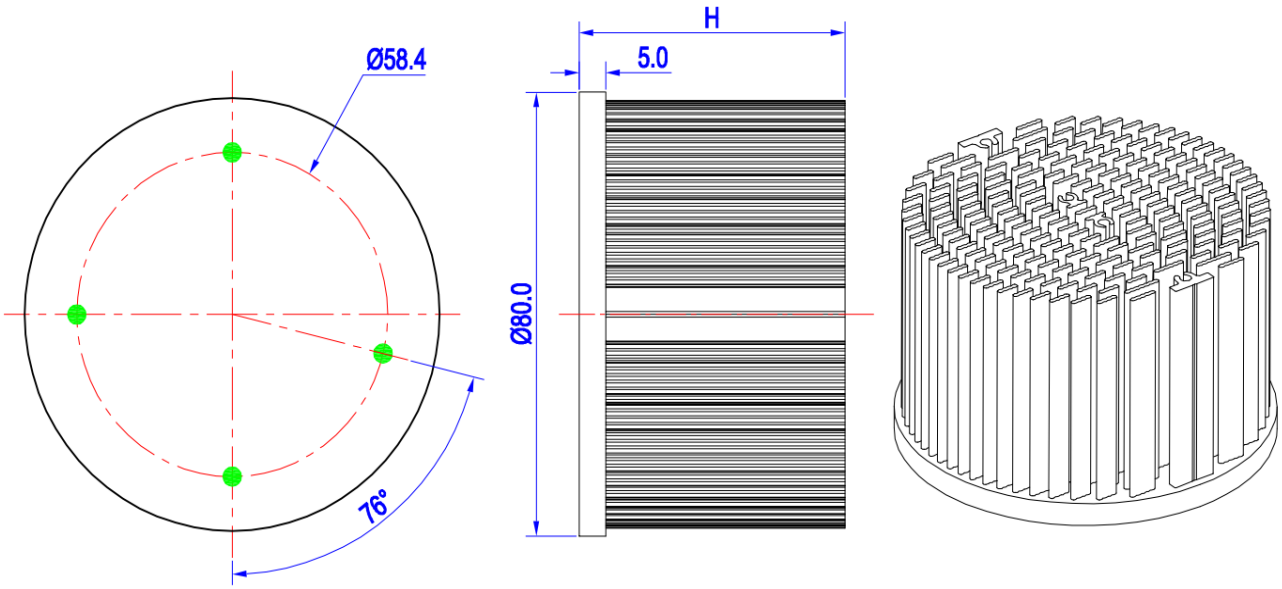
means option 1 and 2 combined

GE Lighting

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	THREAD	THREAD DEPTH	THREAD HOLE DISTANCE
1	Infusion™ M Infusion™ DLM	GE Lighting	M3.5	6.5mm	Φ58.4mm/ 4-M3.5 (Zhaga book5)



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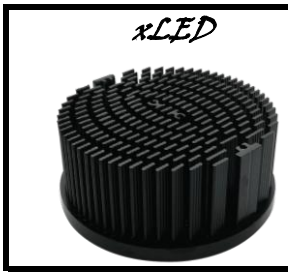
The product deta table



Model No.	**xLED-GE-8030**
Heatsink Size	**Φ80xH30mm**
Heatsink Material	**AL1070**
Finish	**Black Anodized**
Weight (g)	**140.0**
Dissipated power (Ths-amb,50℃)	**16.0** (W)
Cooling surface area (mm^2)	**72123**
Thermal Resistance (Rhs-amb)	**3.13** (°C/W)

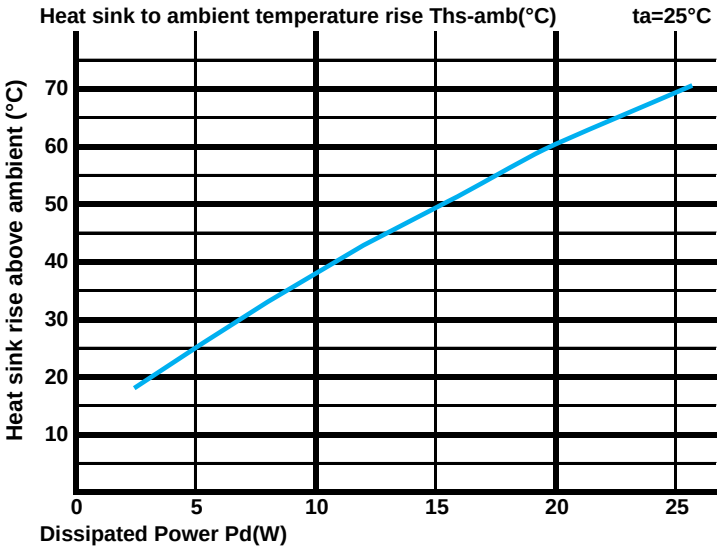
The thermal data table

* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

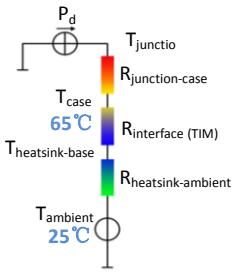
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
		xLED-GE-8030	
Dissipated Power Pd(W)	5.0	5.00	25.0
	10.0	3.80	38.0
	15.0	3.27	49.0
	20.0	3.00	60.0
	25.0	2.76	69.0



*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.
Either thermal grease,A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or Geometric shapes are different, the thermal resistance is different. Formula: θ ＝(Ths－Ta)/Pd
θ - Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface\ (TIM)}$ [°C/W], the thermal heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface\ (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point.Thus, the following formula is $T_{junction}=(R_{junction-case}+R_{case-ambient})\cdot Pd+T_{ambient}$

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